

Specifications

| | |
|--------------|----------------------------|
| Drawing No. | UKY1C-H1-22121-00[37] 1/11 |
| Issued Date. | Mar.3,2022 |

TO: Digi-Key

Note: In case of specification change, KYOCERA Part Number also will be changed.

| | |
|-------------------------------|--|
| Product Type | Quartz Crystal |
| Series | CX2016SA |
| Frequency | 26000kHz |
| Customer Part Number | - |
| Customer Specification Number | - |
| KYOCERA Part Number | CX2016SA26000D0GSSCC |
| Remarks | Pb-Free, RoHS Compliant, MSL 1 AEC-Q200 Compliant |

Customer Approval

| | | |
|--------------------|------------------|--|
| Approval Signature | Approved Date | |
| | Department | |
| | Person in charge | |

Seller

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Manufacturer

RF Devices Division
Corporate Electronic Components Group
Crystal Components Division

| Design Department | Quality Assurance | Approved by | Checked by | Issued by |
|--|--|---|---|---|
| KYOCERA Corporation Crystal Components Application Engineering Section1 RF Devices Division Corporate Electronic Components Group | S. Makimoto  | N. Nakano  | T. Saito  | Y. Kikuchi  |

Revision History

| Rev.No. | Description of revision | Date | Approved by | Checked by | Issued by |
|---------|-------------------------|------------|-------------|------------|------------|
| 00 | First Edition | Mar.3,2022 | N. Nakano | T. Saito | Y. Kikuchi |
| | | | | | |

1. APPLICATION

This specification sheet is applied to quartz crystal "CX2016SA26000D0GSSCC"

2. KYOCERA PART NUMBER

CX2016SA26000D0GSSCC

3. RATINGS

| Items | SYMB. | Rating | Unit | Remarks |
|-----------------------------|-------|-------------|------|---------|
| Operating Temperature Range | Topr | -40 to +125 | °C | |
| Storage Temperature Range | Tstg | -40 to +125 | °C | |

4. CHARACTERISTICS

ELECTRICAL CHARACTERISTICS

| Items | Electrical Specification | | | | | Test Condition | Remarks |
|---------------------------------------|--------------------------|-------------|------|-------|------|----------------------|---|
| | SYMB. | Min | Typ. | Max | Unit | | |
| Mode of Vibration | | Fundamental | | | | | |
| Nominal Frequency | F0 | | 26 | | MHz | | |
| Nominal Temperature | T _{NOM} | | +25 | | °C | | |
| Load Capacitance | CL | 8.0 | | | pF | | |
| Frequency Tolerance | df/F | -15.0 | | +15.0 | PPM | +25±3°C | Based on an oscillation frequency at +25 °C |
| Frequency Temperature Characteristics | df/F | -50.0 | | +50.0 | | -40 to +125°C | |
| Frequency Aging Rate | | -2.0 | | +2.0 | | 1 st year | |
| Equivalent Series Resistance | ESR | | | 60 | Ω | | |
| Drive Level | Pd | 0.01 | | 200 | μW | | |
| Insulation Resistance | IR | 500 | | | MΩ | 100V(DC) | |

5. Measurement Condition

5.1 Frequency measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : 8.0pF

Drive Level : 10 μ W

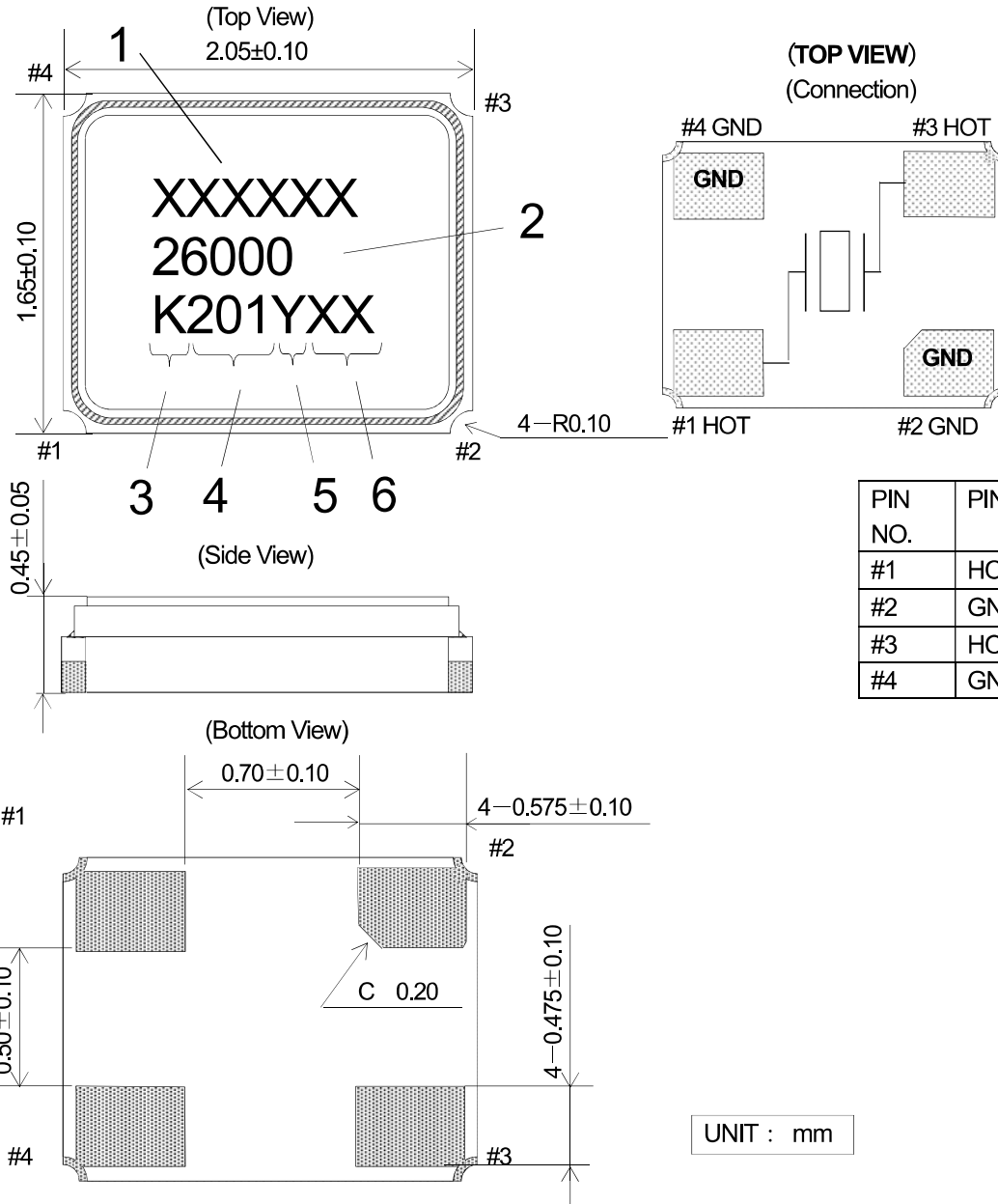
5.2 Equivalent series resistance (ESR) measurement

Measuring instrument : IEC PI-Network Test Fixture

Load Capacitance : Series

Drive Level : 10 μ W

6. APPEARANCES, DIMENSIONS
OUTLINE DIMENSION (not to scale)



| PIN NO. | PIN Layout |
|---------|------------|
| #1 | HOT |
| #2 | GND |
| #3 | HOT |
| #4 | GND |

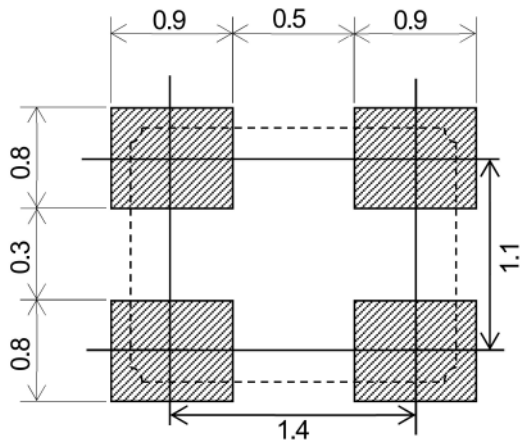
UNIT : mm

MARKING

- 1. Serial Code 6Digits
- 2. Nominal Frequency First 5digit of the frequency is indicated.
- 3. Identification [K] is to indicate 1Pin direction.
- 4. Date Code Last 1 Digit of YEAR and WEEK
 (Ex) 2022,Jan,01 → 201
- 5. Manufacturing Location
 Y...Japan (Yamagata)
 Z...Japan (Shiga Yohkaichi)
 V...Vietnam
- 6. Internal code

※The font of marking is for reference only.

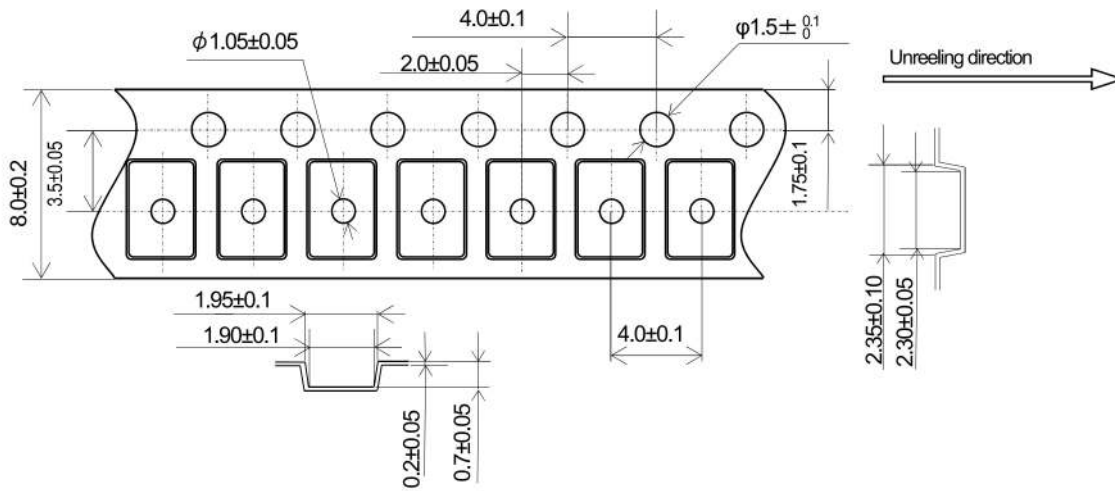
7. RECOMMENDED LAND PATTERN (not to scale)



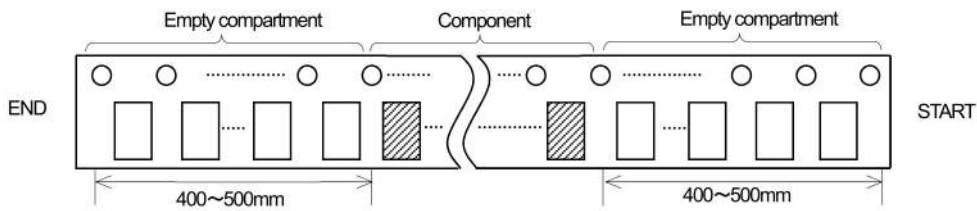
UNIT : mm

8. TAPING & REEL

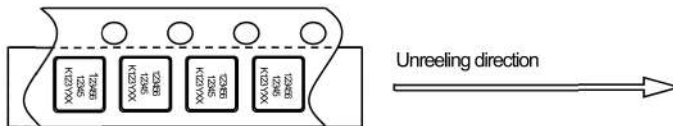
8-1. Dimensions



8-2. Leader and trailer tape

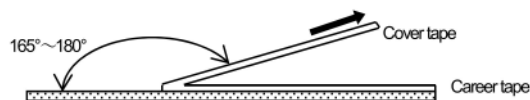


8-3. Direction (The direction shall be seen from the top cover tape side)

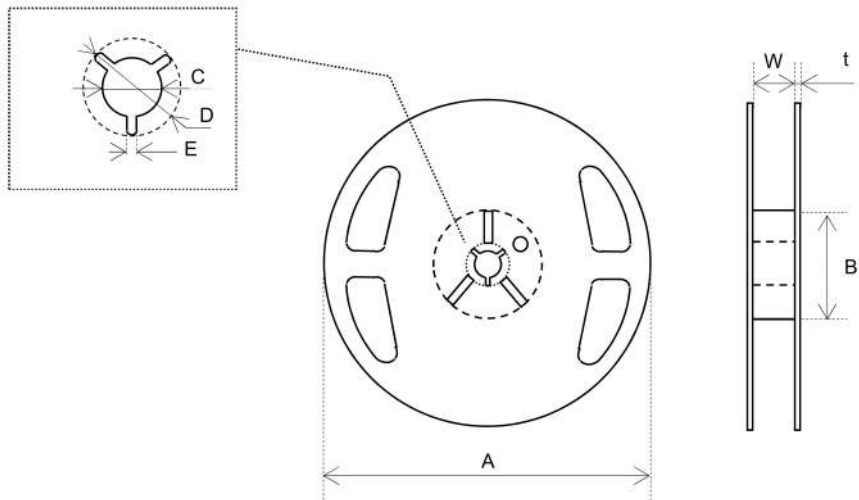


8-4. Specification

1. Material of the carrier tape is either polystyrene or A-PET (ESD).
2. Material of the cover tape is PET/PE (ESD).
3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
4. Tensile strength of carrier tape: 10N or more.
5. The R of the corner of each cavity is $0.2R_{MAX}$.
6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
7. The orientation shall be checked from the top cover tape side as shown in 8-3.
8. Peeling force of cover tape: 0.1 to 1.0N.
9. The component will fall out naturally when cover tape is removed and set upside down.



8-5.Reel Specification



φ180 Reel (3,000pcs Max)

| Symbol | A | B | C | D |
|-----------|------------------|-----------------|-------------------|-------------------|
| Dimension | $\phi 180 +0/-3$ | $\phi 60 +1/-0$ | $\phi 13 \pm 0.2$ | $\phi 21 \pm 0.8$ |
| Symbol | E | W | t | |
| Dimension | 2.0 ± 0.5 | 9 ± 1 | 2.0 ± 0.5 | |

(Unit : mm)

φ330 Reel (15,000pcs Max)

| Symbol | A | B | C | D |
|-----------|--------------------|--------------------|-------------------|-------------------|
| Dimension | $\phi 330 \pm 2.0$ | $\phi 100 \pm 1.0$ | $\phi 13 \pm 0.2$ | $\phi 21 \pm 0.8$ |
| Symbol | E | W | t | |
| Dimension | 2.0 ± 0.5 | 9.5 ± 0.5 | 2.2 ± 0.1 | |

(Unit : mm)

9. ENVIRONMENTAL AND MECHANICAL CHARACTERISTICS :

(Reference: AEC-Q200 Rev. D. The solder used by examination is hereafter set to Sn-3Ag-0.5Cu.)

After following test, frequency shall not change more than $\pm 10 \times 10^{-6}$ and CI, $\pm 20\%$ or 5Ω .

| No | Stress | Reference | Additional Requirements |
|------|-------------------------------------|-------------------------|---|
| 9.1 | High Temperature Exposure (Storage) | MIL-STD-202 Method 108 | 1000 hrs. at rated operating temperature (e.g. 85°C part can be stored for 1000 hrs at 85°C. Same applies for 125°C). Unpowered. Measurement at 24±4 hours after test conclusion. |
| 9.2 | Temperature Cycling | JESD22 Method JA-104 | 1000 cycles (-40°C to 125°C) Note: If 85°C part the 1000 cycles will be at that temperature rating. Measurement at 24±4 hours after test conclusion. 30min maximum dwell time at each temperature extreme. 1 min. maximum transition time. |
| 9.3 | Biased Humidity | MIL-STD- 202 Method 103 | 1000 hours 85°C/85%RH. Rated VDD applied with 1 MW and inverter in parallel, 2X crystal CL capacitors between each crystal leg and GND. Measurement at 24±4 hours after test conclusion. |
| 9.4 | Operational Life | MIL-STD- 202 Method 108 | Note: 1000 hrs @ 125°C. If 85°C part will be tested at that temperature. Rated VDD applied with 1 MW and inverter in parallel, 2X crystal CL capacitors between each crystal leg and GND. Measurement at 24±4 hours after test conclusion. |
| 9.5 | Terminal Strength (Leaded) | MIL-STD- 202 Method 211 | Test leaded device lead integrity only. Conditions: A (227 g), C (227 g). |
| 9.6 | Resistance to Solvents | MIL-STD- 202 Method 215 | Note: Also aqueous wash chemical - OKEM clean or equivalent. Do not use banned solvents. |
| 9.7 | Mechanical Shock | MIL-STD-202 Method 213 | Figure 1 of Method 213. Condition C |
| 9.8 | Vibration | MIL-STD-202 Method 204 | 5g's for 20 minutes 12 cycles each of 3 orientations. Note: Use 8"X5" PCB .031" thick with 7 secure points on one 8" side and 2 secure points on corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz. |
| 9.9 | Resistance to Soldering Heat | MIL-STD-202 Method 210 | Condition B No pre-heat of samples. Note: Single Wave solder - Procedure 1 with solder within 1.5 mm of device body for Leaded. Procedure 1 except 230°C and immerse only to level to cover terminals for SMD. |
| 9.10 | Solder ability | J-STD-002 | For both Leaded & SMD. Electrical Test not required. Magnification 50 X. Conditions: Leaded: Method A @ 235°C, category 3. SMD: a) Method B, 4 hrs @ 155°C dry heat @ 235°C b) Method B @ 215°C category 3. c) Method D category 3 @ 260°C. |
| 9.11 | Flammability | UL-94 | V-0 or V-1 Acceptable |
| 9.12 | Board Flex | AEC Q200-005 | 60 sec minimum holding time. |
| 9.13 | Terminal Strength(SMD) | AEC Q200-006 | - |

10. Soldering condition

- 1.) Material of solder
 Kind ... lead free solder paste
 Melting point ... $+220 \pm 5^{\circ}\text{C}$

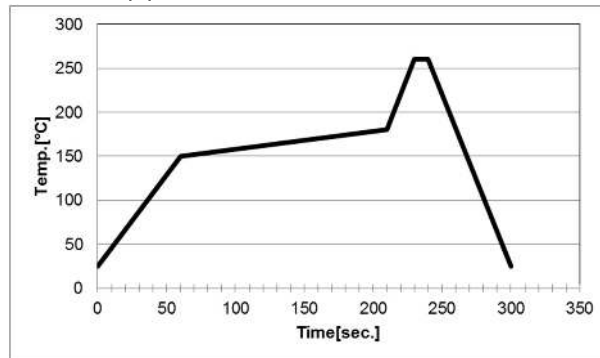
- 2.) Reflow temp.profile

| | Temp [$^{\circ}\text{C}$] | Time[sec] |
|------------|-----------------------------|------------|
| Preheating | +150 to +180 | 150 (typ.) |
| Peak | $+260 \pm 5$ | 10 (max.) |
| Total | — | 300 (max.) |

Frequency shift : $\pm 2\text{ppm}$

- 3.) Hand Soldering $+350^{\circ}\text{C}$ 3 sec MAX
- 4.) Reflow Times 2 times

Reflow temp.profile



11. Cautions for use

- (1) Soldering upon mounting
 There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.
- (2) When using mounting machine
 Please minimize the shock when using mounting machine to avoid any excess stress to the product.
- (3) Conformity of a circuit
 We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 10 times the ESR (Equivalent Series Resistance) of crystal unit.

12. Storage conditions

Please store product in below conditions, and use within 6 months.
 Temperature $+18$ to $+30^{\circ}\text{C}$, and Humidity of 20 to 70 % in the packaging condition.

13. Manufacturing location

Kyocera Corporation Yamagata Higashine Plant / Japan(Yamagata)
 Kyocera Corporation Shiga Yohkaichi Plant / Japan(Shiga)
 Kyocera Vietnam Co., LTD. / Vietnam

14. Quality Assurance

To be guaranteed by Kyocera Corporation Yamagata Higashine Plant Quality Assurance Division

15. Quality guarantee

In case when Kyocera Corporation rooted failure occurred within 1 year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1 year of its delivery is waived.

16. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.